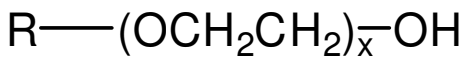
WHAT IS CLAIMED IS:

1. A polishing slurry composition, comprising a non-ionic surfactant represented by formula (1),



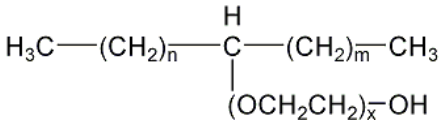
formula (1)

wherein x is an integer between 1 and 50, and wherein the non-ionic surfactant is a secondary alcohol ethoxylate, and a pH value of the polishing slurry composition is between 7 and 11.

2. The polishing slurry composition of claim 1, wherein x is an integer between 7 and 40.

3. The polishing slurry composition of claim 1, wherein R is selected from a group consisting of a C3-C50 alkyl group, a C3-C50 hydroxyalkyl group, a C6-C55 benzylalkyl group and a C6-C55 phenylalkyl group.

4. The polishing slurry composition of claim 1, wherein the non-ionic surfactant is represented by formula (2),



formula (2)

wherein m+n is an integer between 2 and 15.

5. The polishing slurry composition of claim 1, wherein based on a total weight of the polishing slurry composition, a content of the non-ionic surfactant is between 5 ppm and 5000 ppm.

6. The polishing slurry composition of claim 5, wherein based on the total weight of the polishing slurry composition, the content of the non-ionic surfactant is between 10 ppm and 1000 ppm.

7. The polishing slurry composition of claim 1, further comprising an oxidizing agent.

8. The polishing slurry composition of claim 7, wherein the oxidizing agent is one or

more selected from a group consisting of permanganate salt, peroxyacid, iodate salt, oxybromide salt, ceric salt, bromate salt, hydrogen peroxide, chlorite salt and hypochlorite salt.

9. The polishing slurry composition of claim 7, wherein based on a total weight of the polishing slurry composition, a content of the oxidizing agent is between 0.5% and 10%.

10. The polishing slurry composition of claim 1, further comprising polishing particles.

11. The polishing slurry composition of claim 10, wherein based on a total weight of the polishing slurry composition, a content of the polishing particles is between 100 ppm and 5000 ppm.

12. The polishing slurry composition of claim 10, wherein an average diameter of the polishing particles is between 5 nm and 300 nm.

13. The polishing slurry composition of claim 10, wherein an average diameter of the polishing particles is between 5 nm and 100 nm.

14. The polishing slurry composition of claim 10, wherein the polishing particles comprise one or more selected from a group consisting of silicon dioxide, aluminum oxide, cerium oxide, zirconium dioxide and titanium dioxide.

~~15. The polishing slurry composition of claim 1, wherein a pH value of the polishing slurry composition is between 5 and 11.~~

~~16~~15. The polishing slurry composition of claim 1, further comprising a pH adjustor.

~~17~~16. The polishing slurry composition of claim ~~16~~15, wherein the pH adjustor is one or more selected from a group consisting of potassium hydroxide, triethanolamine, 2,2,2-nitrilotriethanol, nitric acid, sulfuric acid, oxalic acid and citric acid.

~~18~~17. The polishing slurry composition of claim ~~16~~15, wherein a content of the pH adjustor is between 5 ppm and 10,000 ppm based on a total weight of the polishing

slurry composition.

~~19~~18. The polishing slurry composition of claim 1, further comprising a chelating agent.

~~20~~19. The polishing slurry composition of claim ~~19~~18, wherein the chelating agent comprises inorganic acids, organic acids or amino acids.

~~21~~20. The polishing slurry composition of claim ~~20~~19, wherein the chelating agent is one or more selected from a group consisting of citric acid, diethylenetriaminepentaacetate, ammonium oxlate, tartaric acid, oxalic acid, maleic acid, lactic acid, succinic acid, histidine, alanine, glycine, aspartate, glutamine, serine and arginine.

~~22~~21. The polishing slurry composition of claim ~~19~~18, wherein a content of the chelating agent is between 0.1% and 10% based on a total weight of the polishing slurry composition.

~~23~~22. The polishing slurry composition of claim 1, further comprising an corrosion inhibitor.

~~24~~23. The polishing slurry composition of claim ~~23~~22, wherein said corrosion inhibitor is one or more selected from a group that consists of 1-H-benzotriazole, N-acyl sarcosinate, ammonium dodecylsulfate, tolyltriazole, 5-amino tetrazole, 3-amino-1,2,4-triazole, 4-amino-4H-1,2,4-triazole, 3-nitro-1,2,4-triazole, 3-mercapto-1,2,4-triazole, 1H-1,2,3-triazole-ethanol, benzimidazole, imidazole, pyrrole, pyrroline, oxazole, isoxazole, indazole, indolizine, 1,2,3-triazole, 1,2,4-triazole, methylbenzotriazole, 2-mercaptobenzothiazole, benzylidene dioxotetrahydro thiazole, thenylidene dioxotetrahydro thiazole and dodecylbenzene sulfonic acid.

~~25~~24. The polishing slurry composition of claim ~~23~~22, wherein a content of the corrosion inhibitor is between 1 ppm and 1000 ppm based on a total weight of the polishing slurry composition.

~~26~~25. The polishing slurry composition of claim 1, further comprising an aqueous carrier.

~~27~~26. The polishing slurry composition of claim ~~26~~25, wherein a content of the aqueous carrier is between 50% and 99% based on a total weight of the polishing slurry composition.

~~28~~27. The polishing slurry composition of claim ~~26~~25, wherein the aqueous carrier comprises deionized water.